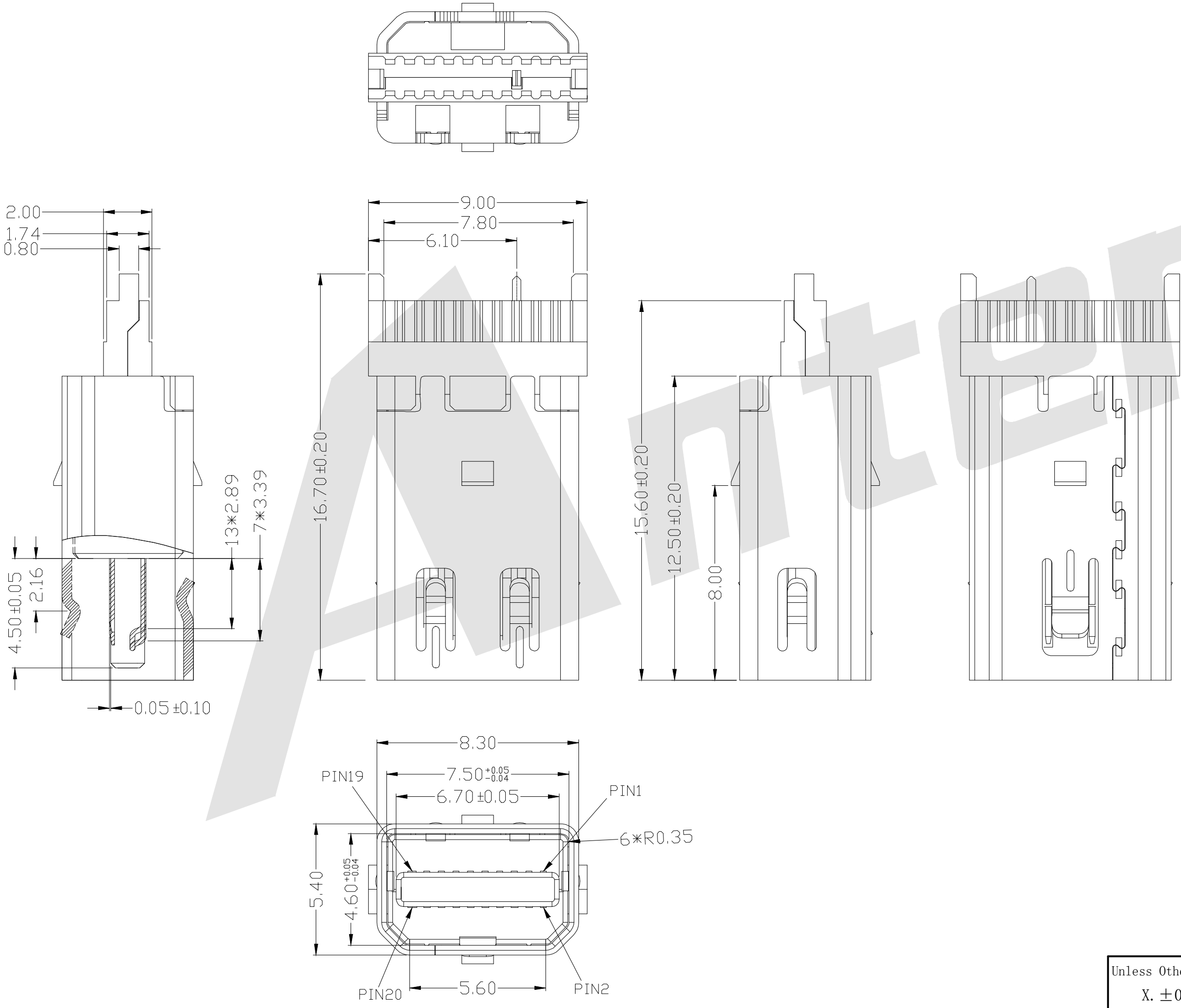
HSF Pb RoHS



notes:
1. materil
1.1 housing:LCP (UL94-V-0),black.
1.2 contact:copper alloy(T=0.20)
plating:gold plated on contact area,
tin plated on solder tails,under nickel plated.
1.3 shell:brass(T=0.40),plating:nickel plated.
1.4 cover:LCP,plastic(UL94V-0)black,
2 specification:
2.1 current rating:0.5 A
2.2 contact resistance:30 milliohms max
2.3 dielectric withstanding voltage:500 AC
R.M.S fou one minute.
2.4.insulation resistanc:100 milliohms min
2.5. operation temperature:-25℃ ~+85℃ .
2.6. durability:10000 cycles
2.7. mating force: 4.5 KG max.
2.8. unmating force:1.0 KG min.

Ordering Code:

MDP - F - X - X - 03
① ② ③ ④ ⑤

① Series No:

② Male/female:
F:female

③ Contact Plating:
1: Selective 1u"
2: Selective 3u"
3: Selective 5u"
4: Selective 15u"
5: Selective 30u"
6: All Golld

④ Shell Plating:
1:NICKKL PLATK
2:TIN-LKAD PLATED
3:GOLD PLATKD

⑤ series number:
03

Unless Otherwise specified tolerance
X. ±0.35 X.XX:±0.20
X.X:±0.25 X.XXX:±0.15

SCALE: As Shown
UNIT: mm
DRAW Mo Guo Xuan
DATE 29/10/2018
CHECK BobYang
DATE 29/10/2018

3rd ANGLE PROJECTION

Antenk®
ANTENK ELECTRONICS CO,.LTD
Http://www.antenk.com
E-mail:sales@antenk.com

TITLE:
mini display receptcle solder type

DRAWING NO: MDP-FXX03
PRODUCT NO: MDP-FXX03

REV	DESCRIPTION	DATE

Antenk